

6N137

Super **High** Speed Response OPIC Photocoupler

■ Features

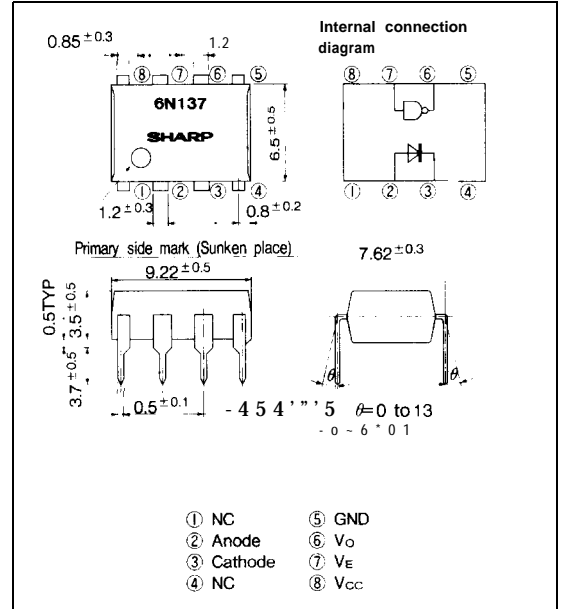
1. Super high speed response
(t_{PHL}, t_{PLH} : TYP. 45ns at $R_L=350\Omega$)
2. Isolation voltage between input and output
 $V_{iso} : 2\ 500V_{rms}$
3. Low input current drive (I_{FHL} : MAX. 5mA)
4. Instantaneous common mode rejection voltage
CMH : TYP. 500V/ μ s
5. LSTTL and TTL compatible output
6. Recognized by UL , file No. E64380

■ Applications

1. High speed interfaces for computer peripherals, microcomputer systems
2. High speed line receivers
3. Noise reduction
4. Interfaces for data transmission equipment

■ Outline Dimensions

(Unit : mm)



"OPIC" (Optical IC) is a trademark of the SHARP Corporation
An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.

(Ta = 25°C)

■ Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Input	*1 Forward current	I_F	20	mA
	*2 Peak forward current	I_{Fp}	40	mA
output	Reverse voltage	V_R	5	V
	Supply voltage	V_{CC}	7	V
	Enable voltage	C_E	5.5	v
	High level output voltage	V_{OH}	7	v
	Low level output current	I_{OL}	50	mA
	Output collector power dissipation	P_C	85	mW
	*5 Isolation voltage	V_{iso}	2 500	V_{rms}
Operating temperature		T_{opr}	0 to +70	°C
Storage temperature		T_{stg}	-55 to +125	°C
*6 Soldering temperature		T_{sol}	260	°C

*1 Ta=0 to 70°C

*2 Pulse width \leq 1ms

*3 For 1 minute MAX.

*4 Not exceed 500mV or more than supply voltage (V_{CC})

*5 AC for 1 minute, 4f) to 60% RH

Apply the specific voltage between all the input electrode pins connected together and all the output electrode pins connectef together.

*6 2mm or more away from the lead base for 10 seconds

■ Electro-optical Characteristics

(Ta = 0 to + 70°C unless otherwise specified)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Logic (1) output current	I _{OH}	V _{CC} =5.5V, V _O =5.5V, I _F =250 μA, V _E =2.0V	—	2	250	μA
Logic (0) output voltage	V _{OL}	V _{CC} =5.5V, I _F =5mA, V _{EH} =2.0V, I _{OL} (Sinking) =13mA	—	0.4	0.6	V
Logic (1) enable current	I _{EH}	V _{CC} =5.5V, V _E =2.0V	—	-0.8	—	mA
Logic (0) enable current	I _{EL}	V _{CC} =5.5V, V _E =0.5V	—	-1.2	-2.0	mA
Logic (1) supply current	I _{CCH}	V _{CC} =5.5V, I _F =0mA, V _E =0.5V	—	7	15	mA
Logic (0) supply current	I _{CCL}	V _{CC} =5.5V, I _F =10mA, V _E =0.5V	—	13	18	mA
*Leak current	I _{LO}	45% RH, Ta=25°C, I _F =3, V _O =3.00V _±	—	—	1.0	μA
*1 Isolation resistance (input-output)	R _{IO}	V _{LO} =500V, Ta=25°C	—	10 ¹²	—	Ω
*1 Capacitance (input output)	C _{IO}	f=1MHz, Ta=25°C	—	0.6	—	pF
*2 Input forward voltage	V _F	I _F =10mA, Ta=25°C	—	1.6	1.75	v
Input reverse voltage	BVR	I _R =10 μA, Ta=25°C	5	—	—	V
Input capacitance	C _{IN}	V _F =0, f=1 MHz	—	60	—	pF
*3 Current transfer ratio	CTR	I _F =5.0mA, R _L =100 Ω	—	700	—	%
*4 Propagation delay time output (o) → (1)	t _{PH}	Ta=25°C, V _{CC} =5V, R _L =350Ω, C _L =15pF, I _F =7.5mA	—	45	75	ns
*5 Propagation delay time output (1) → (o)	t _{PHI}	Ta=25°C, V _{CC} =5V, R _L =350Ω, C _L =15pF, I _F =7.5mA	—	45	75	ns
Output rise-fall time (10 to 90%)	t _r , t _f	R _L =350 Ω, C _L =15pF, I _F =7.5mA	—	20, 30	—	ns
*6 Enable propagation delay time (1) → (0)	t _{ELH}	R _L =350Ω, C _L =15pF, I _F =7.5mA, V _{EH} =3.0V, V _{EL} =0.5V	—	40	—	ns
*7 Enable propagation delay time (0) → (1)	t _{EHL}	R _L =350Ω, C _L =15pF, I _F =7.5mA, V _{EH} =3.0V, V _{EL} =0.5V	—	15	—	ns
*8 Instantaneous common mode rejection VOItage "output (o)"	CM _H	V _{CM} =10V, R _L =350Ω, V _O (min) =2V, I _F =0mA	—	500	—	V/μs
*8 Instantaneous common mode rejection voltage "output (1)"	CM _L	V _{CM} =10V, R _L =350Ω, V _O (min) I-0.8%, I _F =5mA	—	-500	—	V/μs

Note) Typical values are all at V_{CC} 5V, Ta = 25°C

- *1 Measured as 2-pin element, Connect pins 2 and 3, connect pins 5, 6, 7 and 8.
- *2 At I_F=10mA, V_F decreases at the rate of 1.6mV/°C if the temperature goes up.
- *3 DC current transfer ratio is defined as the ratio of output collector current to forward bias input current.
- *4, *5 Refer to the Fig. 1.
- *6, *7 Refer to the Fig. 2.
- *8 CM_H represents a common mode voltage ignorable rise time ratio that can hold logic(1) state in output
CM_L represents a common mode voltage ignorable fall time ratio that can hold logic (0) state in Output

■ Recommended Operating Conditions

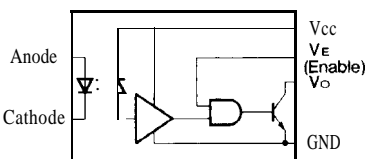
Parameter	Symbol	MIN.	MAX.	Unit
Low level input current	I _{FL}	0	250	μA
High level input current	I _{FH}	*6.3	15	mA
High level enable voltage	V _{EH}	2.0	V _{CC}	V
Low level enable voltage	V _{EL}	0	0.8	V
Supply voltage	V _{CC}	4.5	5.5	v
Fanout (TTL load)	N	—	8	—
Operating temperature	T _{opr}	0	70	°C

1. No necessary external pull-up resistor to hold enable input at high level

2. Connect a ceramic by-pass capacitor (0.01 to 0.1 μF) between V_{CC} and GND at the position within 1 cm from pin.

3. *20% guard band, switching threshold for degradation of CTR are 5mA or less at initial value.

Circuit Block Diagram



Truth Table

Input	Enable	Output
H	H	L
L	H	H
H	L	H
L	L	H

L: Logic (0) H: Logic (1)

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Fig.1 Test Circuit for Propagation Delay time

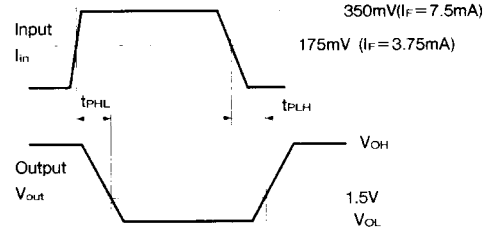
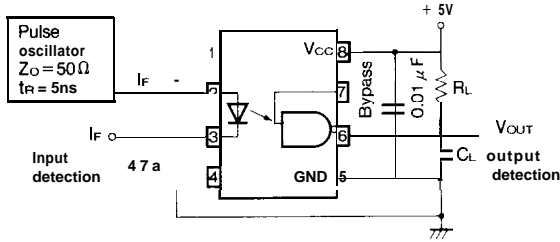


Fig.2 Taat Circuit for Enable Propagation Delay Time

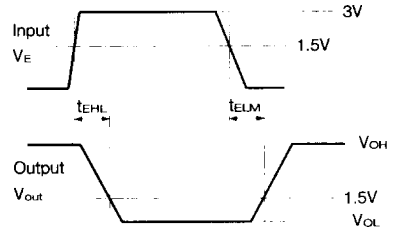
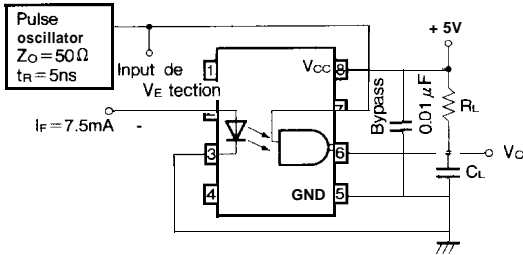


Fig.3 Taat Circuit for Instantaneous common Mods Rejection Voltage

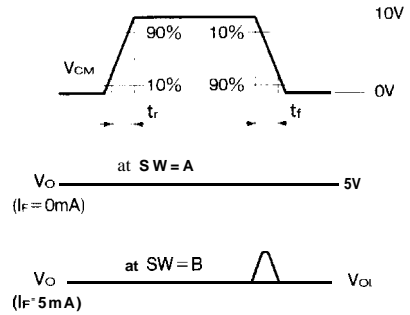
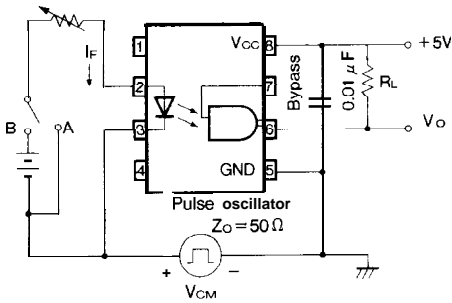


Fig. 4 Output Collector Power Dissipation vs. Ambient Temperature

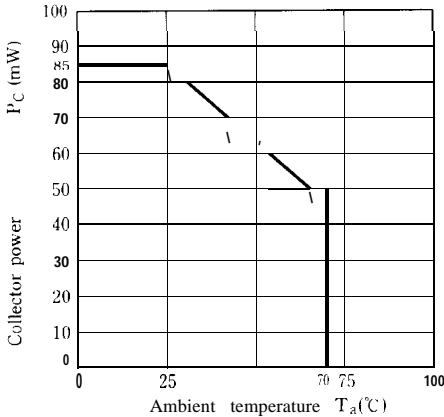


Fig. 5 Forward Current vs. Forward Voltage

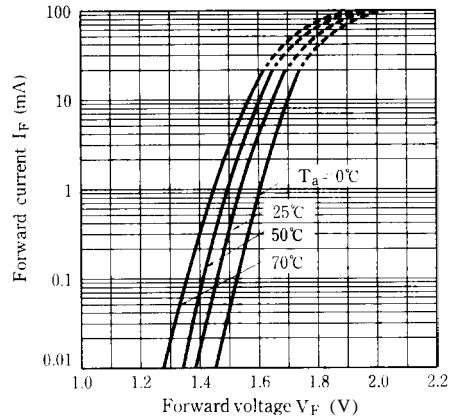


Fig. 6 High Level Output Current vs. Ambient Temperature

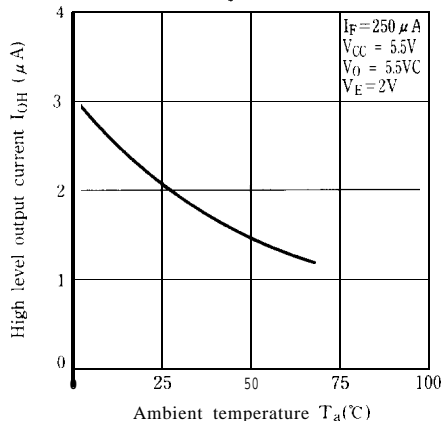


Fig. 7 Low Level Output Voltage vs. Ambient Temperature

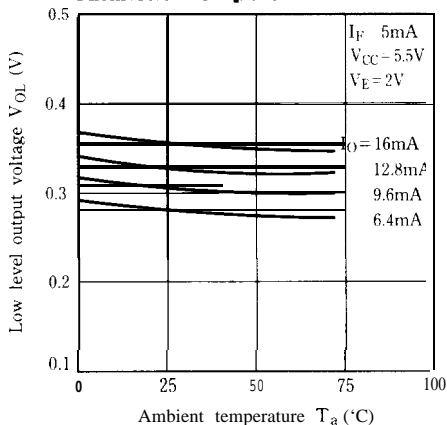


Fig. 8-a Output Voltage vs. Forward Current

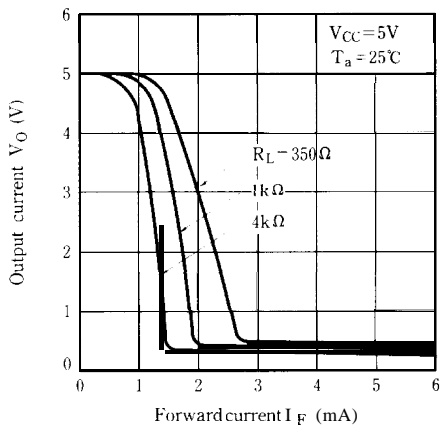


Fig. 8-b Output Voltage vs. Forward Current (Ambient Temp. Characteristics)

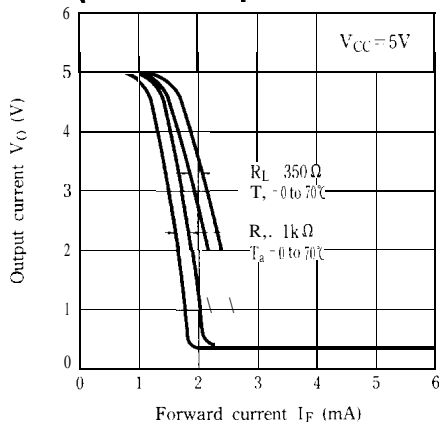


Fig. 9 Propagation Delay Time vs. Forward Current

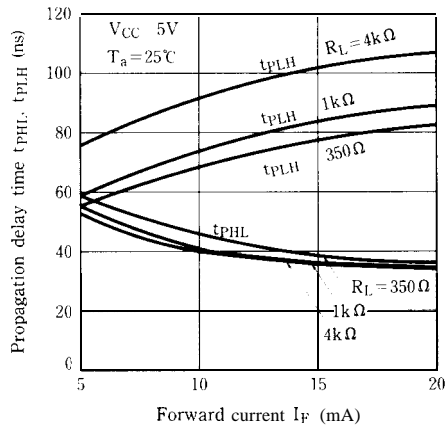
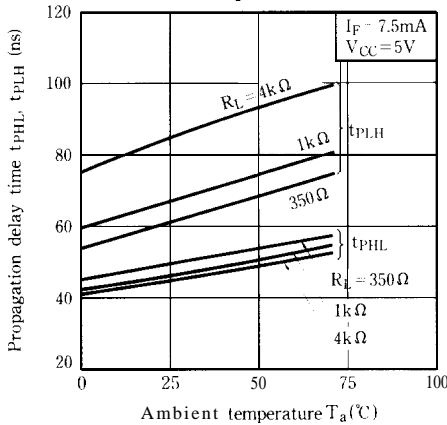


Fig. 10 Propagation Delay Time vs. Ambient Temperature



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Fig.11 Rise Time, Fall Time vs. Ambient Temperature

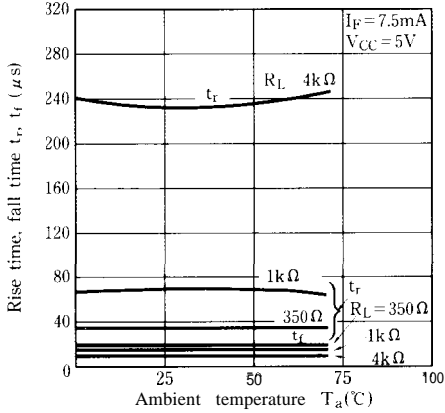
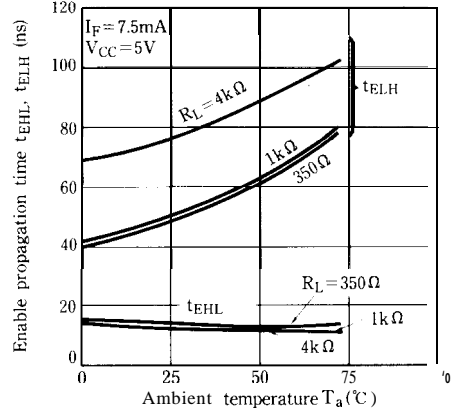


Fig.12 Enable Propagation Time vs. Ambient Temperature



■ precautions for use

- Handle this product the same as with other integrated circuits against static electricity.
- Please refer to the chapter "Precautions for Use" . (Page 78 to 93)